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surface acoustic wave absorbing member, and the first element surface being disposed in an opposite relation with respect to the first board surface; and

a conductive connecting member disposed between the board wiring pattern and the element wiring pad, the conductive connecting member being composed of a plurality of bumps stacked according to a spacing between the board wiring pattern and the element wiring pad.

171. The surface acoustic wave device as set forth in Claim 170, wherein a thickness of the conductive connecting member is larger than a thickness of the surface acoustic wave absorbing member.--

REMARKS

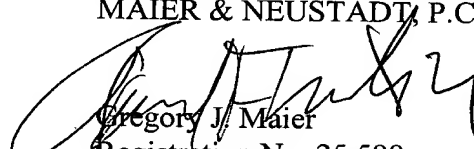
Favorable consideration of this application is respectfully requested.

Claims 166-171 are presently active in this application. Original Claims 1-165 have been canceled without prejudice or disclaimer.

In light of the above, an early and favorable examination on the merits as to the presently active Claims 166-171 is respectfully requested.

Respectfully submitted,

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